

# PATENT ABSTRACTS OF JAPAN

(11)Publication number : 03-030352

(43)Date of publication of application : 08.02.1991

(51)Int.Cl.

H01L 21/66

(21)Application number : 01-164744

(71)Applicant : MITSUBISHI ELECTRIC CORP

(22)Date of filing : 27.06.1989

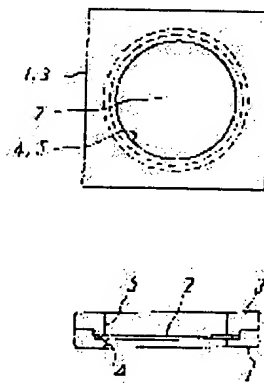
(72)Inventor : MAKIDERA YOSHIKO  
MITSUZAWA TETSUHIRO

## (54) INSPECTION JIG FOR SEMICONDUCTOR WAFER

(57)Abstract:

PURPOSE: To inspect both the surface and rear of a wafer without positioning wafer itself to another place again by holding and fixing the wafer between an inspection plate body having a large inspection window and a cover having a large inspection window.

CONSTITUTION: An inspection window 4 having a large diameter is bored in the inspection plate body 1 of a semiconductor-wafer inspection jig, and a cover 3 having a large inspection window 5 is provided. Consequently, a wafer 2 is held and fixed between the inspection plate body 1 and the cover 3, thus visually inspecting both the surface and rear of the wafer respectively through the inspection window 4 having the large diameter or the inspection window 5 having the large diameter without positioning the wafer to another place again. Accordingly, the deterioration of quality can be prevented by inspection without pressure-welding, marring or contaminating the surface and rear of the wafer.



## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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